COJ1  COH1  COJ4  PAD2201  PAD2202  PAJ401  PAJ402  PAJ108  COZ1  COZ2  COZ3  COZ6  PAD2001  COR28  COR11  PAD2004  COC22  PAR2702  PAR2701  PAC2202  PAR1502  PAR1102  PAR1501  PAC1002  PAC1001  PAU206  PAU205  PAU1302  PAU1301  PAC301  PAC302  PAC2002  PAC201  J1  D22  S2  L1  L2  L3  H3  H2  H1  J6  U4  U10  U8  U8  U6  L4  S1  S1  L5  L5  J4  J5  J3  J2  J1  C2  C1  J8  LBL1

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: D01

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<th>REV: E2</th>
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<td>GENERATED : 7/5/2017 11:03:46 AM</td>
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